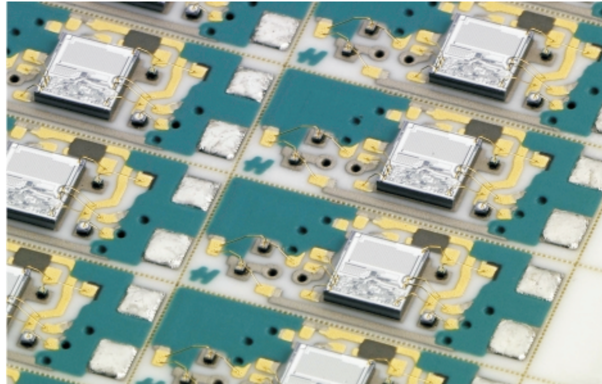
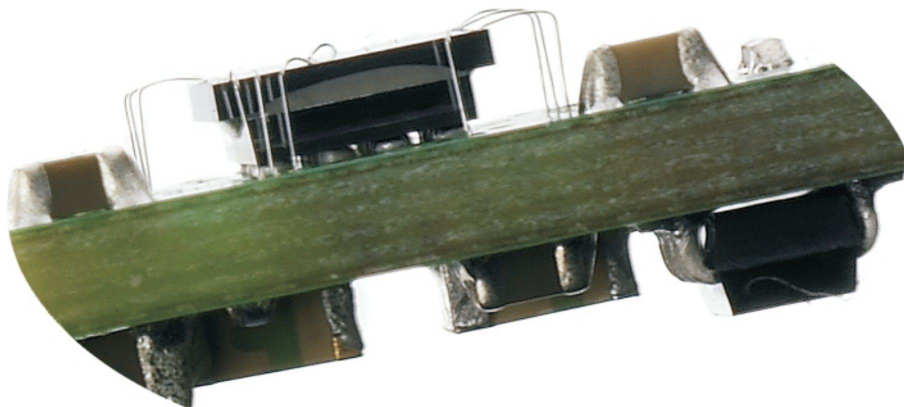
TECHNOLOGY

DIE BONDING

CHIPS SIZE:	SIDE 0.2 - 10mm THICKNESS 50µm	**SUBSTRATES:**	THICK FILM CERAMIC FR4, Fr5, G10, G11, ROGERS FLEX, RIGID FLEX, IMS PYREX ...
TRACEABILITY:	WAFER MAPPING		
POSITIONING ACCURACY:	STANDARD +/- 30µm SPECIFIC +/- 15µm	**ADHESIVES:**	CONDUCTIVE NON-CONDUCTIVE SILICONE
PACKAGING:	WAFER UP TO 8" WAFFLE PACK 2 - 4" GELPACK	**ADHESIVE APPLICATION:**	STAMPING DISPENSING SILK SCREEN PRINTING



HYBRID SA IS ABLE TO BOND CHIPS OF DIFFERENT SIZE AND THICKNESS ON DIFFERENT TYPES OF SUBSTRATES.
POSITIONING ACCURACY AND OTHER PRODUCT SPECIFICATIONS ARE DETERMINED IN COLLABORATION WITH THE CLIENT.



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